

IN THE CLAIMS

A listing of the claims presented in this patent application appears below. This listing replaces all prior versions and listing of claims in this patent application.

1. (Original) A bonding wire comprising a core and a coating layer formed on the core, wherein the coating layer is formed from a metal having a higher melting point than the core, and the wet contact angle with the coating layer when the core is melted is not smaller than 20 degrees.

2. (Original) A bonding wire comprising a core composed mainly of copper and a coating layer formed on the core, wherein the coating layer is formed from an oxidation resistant metal having a higher melting point than the core, and wherein when the bonding wire is hung down with its end touching a horizontal surface, and is cut at a point 15 cm above the end and thus let drop onto the horizontal surface, the curvature radius of the formed arc is 35 mm or larger.

3. (Original) The bonding wire according to claim 2, wherein the curvature radius of the formed arc is 40 mm or larger.

4. (Original) A bonding wire comprising a core composed mainly of copper and a coating layer formed on the core, wherein the coating layer is formed from an oxidation resistant metal having a higher melting point than the core, and wherein the 0.2% yield strength is not smaller than $0.115 \text{ mN}/\mu\text{m}^2$ but not greater than $0.165 \text{ mN}/\mu\text{m}^2$.

5. (Original) The bonding wire according to claim 4, wherein the 0.2% yield strength is not smaller than $0.125 \text{ mN}/\mu\text{m}^2$ but not greater than $0.155 \text{ mN}/\mu\text{m}^2$.

6. (Original) A bonding wire comprising a core and a coating layer formed on the core, wherein the coating layer is formed from a metal having a higher melting point than the core, and wherein the Vickers hardness of the coating layer is 300 or lower.

7. (Original) The bonding wire according to claim 1 or 6, wherein the core material is composed mainly of copper.

8. (Currently Amended) The bonding wire according to ~~any one of claims 2—5 and 7~~ claim 2 or 4, wherein the coating layer is formed from a metal whose melting point is at least 200°C higher than that of copper.

9. (Currently Amended) The bonding wire according to any one of ~~claims 2—5, 7 and 8~~ claims 2, 4 and 7, wherein the elongation per unit cross sectional area is 0.021% / μm^2 or more.

10. (Currently Amended) The bonding wire according to ~~any one of claims 2—5 and 7~~ claim 2 or 4, wherein the core contains other elements than copper in a total amount not smaller than 0.001 weight percent but not larger than 1 weight percent relative to the weight of the core.

11. (Original) The bonding wire according to claim 1 or 6, wherein the core material is composed mainly of silver.

12. (Original) The bonding wire according to claim 6, which has a coating layer B whose Vickers hardness is 150 or less, outside of the coating layer, as the utmost layer.

13. (Original) The bonding wire according to claim 12, wherein the material for the coating layer B is gold.

14. (Currently Amended) The bonding wire according to claim 12 ~~or 13~~, wherein the thickness of the coating layer B is smaller than that of the coating layer and not larger than 0.002 times the wire diameter.

15. (Currently Amended) The bonding wire according to any one of ~~claims 1—14~~ claims 1, 2, 4 and 6, wherein the coating layer is formed from a metal composed mainly of at least one element selected from the group consisting of palladium, platinum, and nickel.

16. (Original) The bonding wire according to claim 15, wherein the coating layer is formed from palladium.

17. The bonding wire according to any one of ~~claims 1—16~~ claims 1, 2, 4 and 6, wherein the thickness of the coating layer falls within the range satisfying as $0.007 \leq Y \leq 0.05$, where $Y = (\text{cross sectional area of coating layer} / \text{cross sectional area of core})$ in the cross section when the wire is cut vertically.

18. (Currently Amended) The bonding wire according to any one of ~~claims 1—17~~ claims 1, 2, 4 and 6, wherein a different metal layer is provided between the core and the coating layer.

19. (Currently Amended) An integrated circuit device that is produced by using the bonding wire according to any one of ~~claims 1—18~~ claims 1, 2, 4, 6 and 15.